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Invensas to Exhibit 3D Interconnect and Bonding Solutions at European MEMS Summit

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq: TSRA), announced today that its wholly owned subsidiary Invensas Corporation will exhibit advanced bonding and 3D interconnect solutions at the upcoming European MEMS Summit, taking place September 15-16 in Stuttgart, Germany.

Sitaram Arkalgud, vice president, 3D Applications at Invensas will deliver a presentation titled, "Using Low Cost of Ownership Direct Bonding Technologies for MEMS Applications."

What: European MEMS Summit

Date: September 15-16, 2016

Location: Maritim Hotel Stuttgart, Stuttgart, Germany

Booth Number: 14

Registration Information: Conference attendees can register for the show at

<http://semi.inviteo.fr/EuropeanMEMSSummit2016/>.

Details: At the show, Invensas will showcase ZiBond® low temperature homogeneous, direct bonding technology that forms a strong bond between wafers or die with same or different coefficients of thermal expansion. Invensas will also showcase Direct Bond Interconnect (DBI®) low temperature hybrid direct bonding technology for wafer and die level 3D interconnect applications.

ZiBond and DBI technologies are cost-effective, versatile 2.5D and 3D semiconductor integration solutions that enable leading edge functionality and accelerate time to market for MEMS and multiple other semiconductor products.

For more information about ZiBond and DBI technologies, visit www.invensas.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

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